

WIRE BONDING APPARATUS AND BONDING METHOD

ABSTRACT

Provided is a wire bonding apparatus capable of performing high-speed wedge wire bonding, the apparatus including: a bonding tool having a through hole and a pressing surface for pressing a wire; a clamper for holding the wire; and a control unit. The control unit includes: wire tail extension means that moves the bonding tool, after wedge bonding of the wire to a first lead, upward and along a second straight line connecting a second pad and a second lead, and causes the wire to extend from the through hole in a direction along the second straight line from the second pad to the second lead; and tail cut means that, after causing the wire tail to extend, cuts the wire tail by moving the bonding tool in the direction along the second straight line connecting the second pad and the second lead while the clamper is closed.

Figures 6a and 6b